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Qualified	isqualified	T 201	6. 05. 16	
Adr NO.1,Xianke N	i Road,Huadong Towr	n, Huadu Distric	t, Guangzhou, Chi n	a
Tel / 020-86 Web/ www.ho	733333 Fax/ nglitronic.com	020-867338	83 86733938	86733265
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- 1. Product naming rules
- 2. Features
- 3. Application range
- 4. Radiation Pattern

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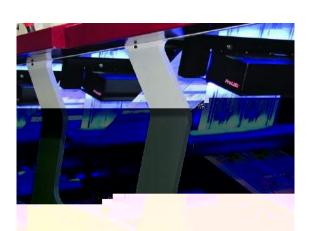
- **5.Typical Optical/Electrical Characteristics Curves**
- 6.Absolute Maximum Ratings
- 7. Package Dimensions
- 8. Welded plate Dimensions
- 9.Label
- **10.Tape Specifications**
- **11.Reflow soldering instructions**
- 12.Use the matters needing attention





Application range

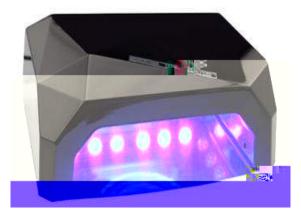




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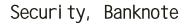
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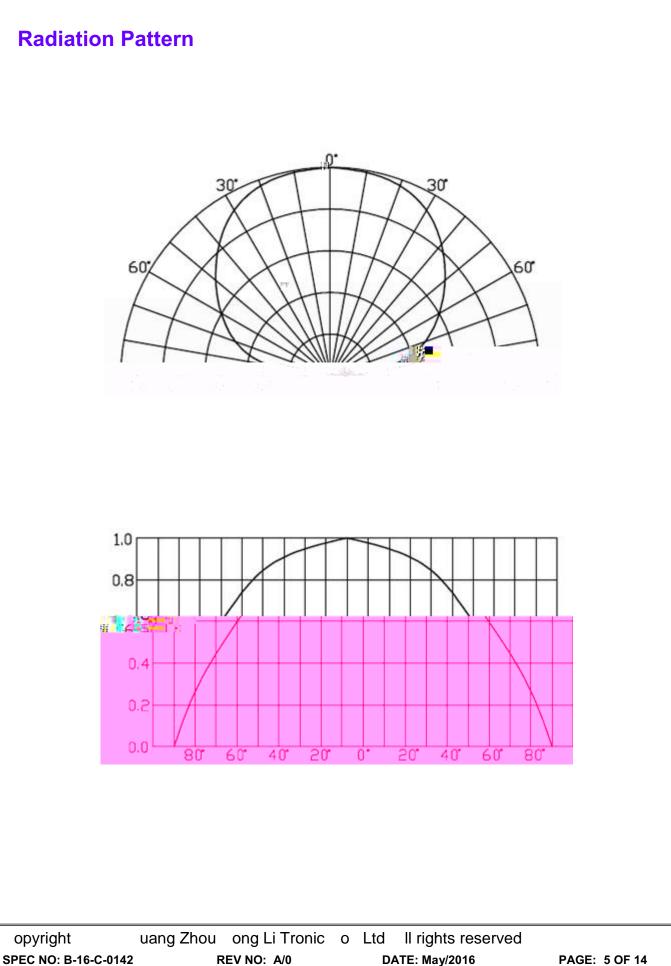


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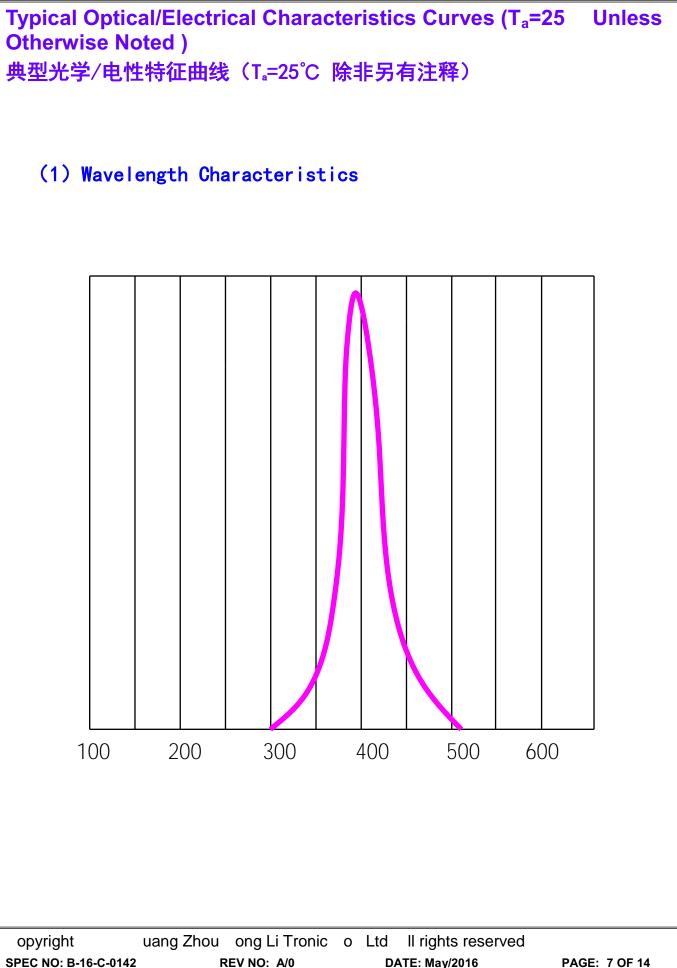
Typical Optical/Electrical Characteristics @Ta=25§7 HmdY

Symbol	ltem	Min.	Тур.	Max.	Units	Test Conditions
е	Radiation lux辐射功率				mW	m
V	orward Voltage 正向电压		_		V	m
Р	Peak Wavelength				nm	m
	Power ngle	_		_	deg	m
R	Reverse urrent	_	_		u	VR V
L	Life Time		_	_	our	m
L	Life Time	—		_	our	m

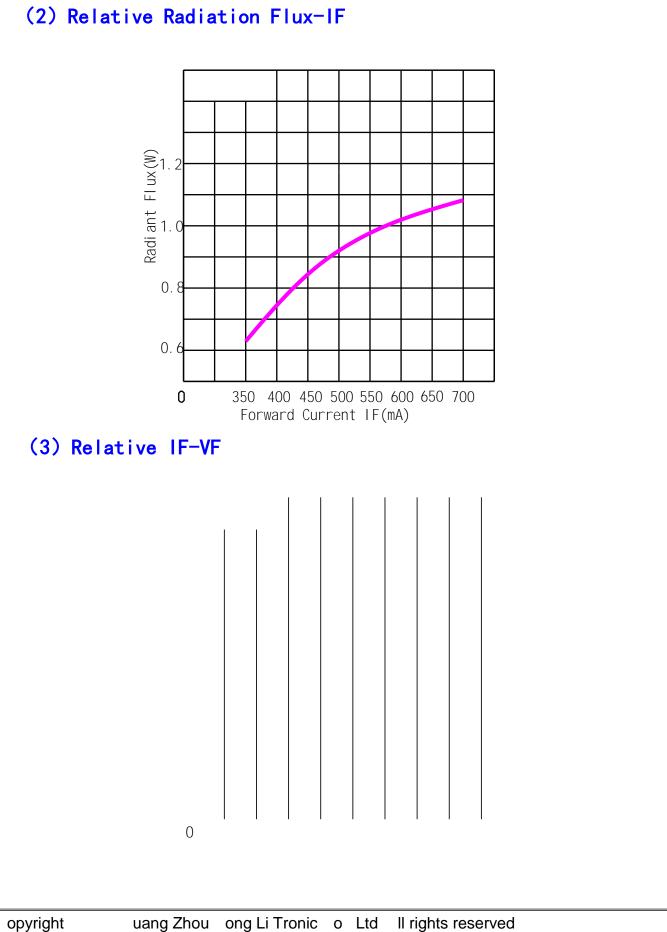
Absolute Maximum Ratings 绝对最大额定值@H51&)š7

Item名称	Symbol 符号	Absolute Maximum Rating 绝对最大额定值	Units
Power dissipation	Pd		W
Peak orward urrent	р		m
Reverse Voltage	V _R		V

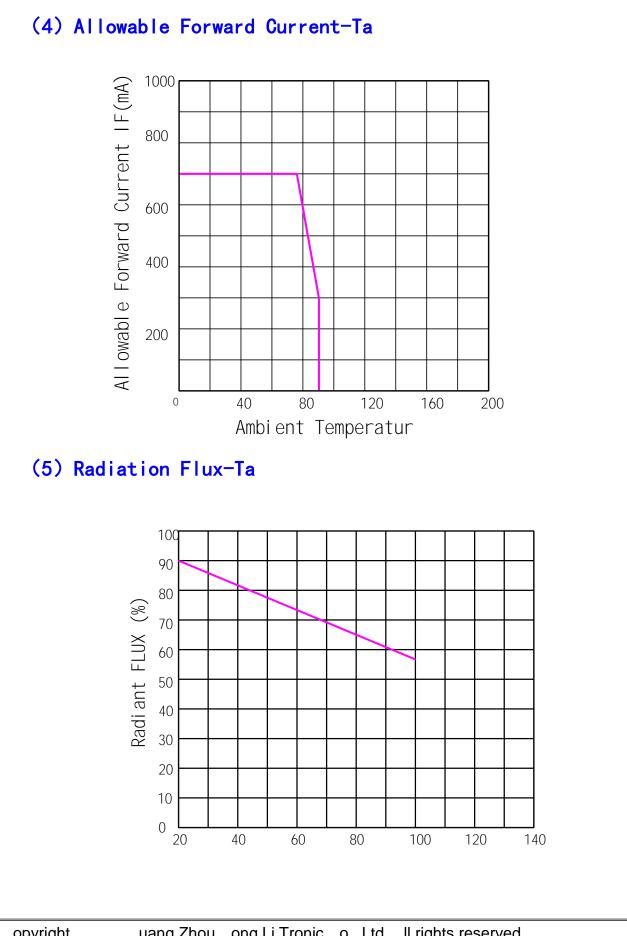






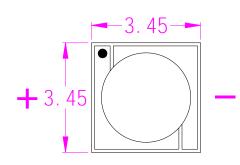


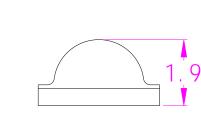


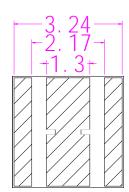




Package Dimensions







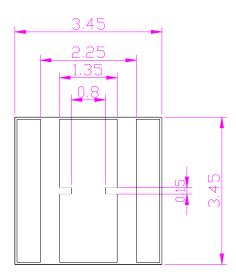
Notes

Il dimension units are millimeters

2. All dimension tolerance is ±0.1mm unless otherwise noted.

Welded plate Dimensions

±



Notes :

When the circuit configuration is not affected suggested the increase in the middle of the copper area or the connection between the middle and the pad and the negative electrode can improve the cooling performance of the product t is recommended to use mmthickness of steel mask

mm



Label

- TYP : XXXXXXXXX
- QTY XXXXX
- V orward voltage rank
 - e Radiation lux rank

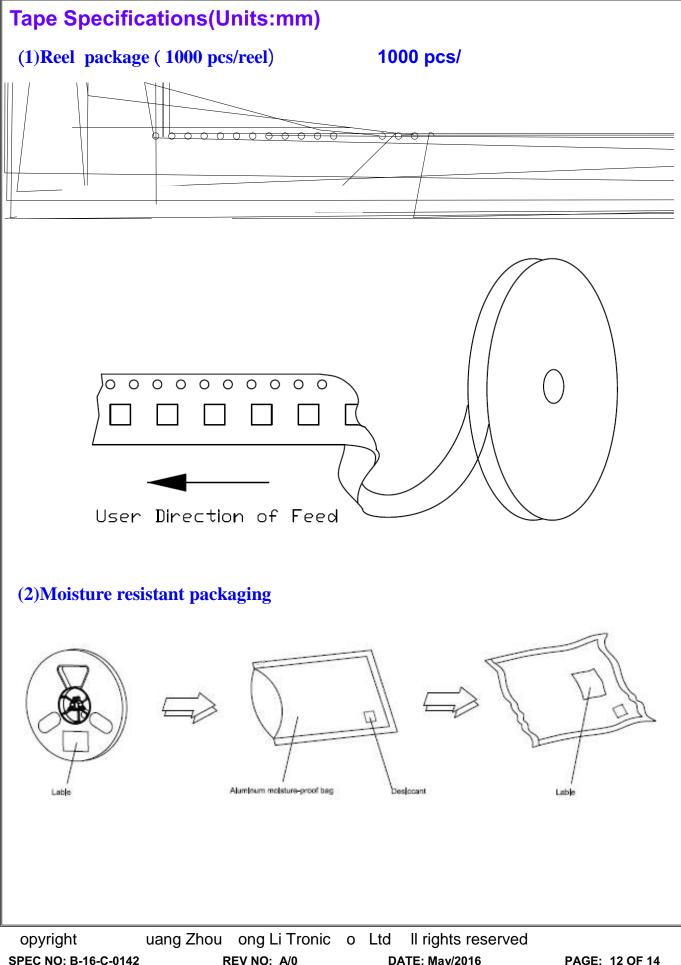
XXXX

- P Peak Wavelength
 - T XXXX

LOT NO Lot Number

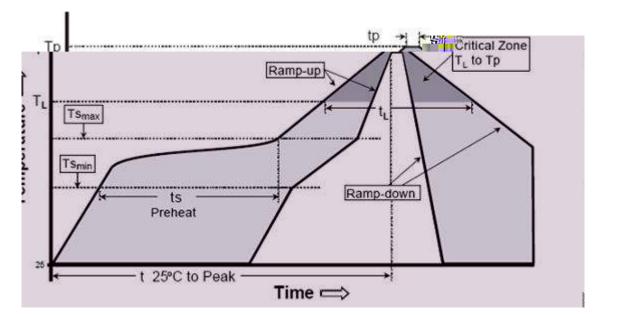
1	HONGLITRONIC 鸿利光电		RoHS
TYPE: VF: IF: DATE		QTY: e: P: LOT. NO:	







Reflow soldering instructions



Profile Feature	Lead-Based solder	Lead-Free Solder
verage Ramp Rate Ts _{max} to Tp	second max	second max
Preheat Temperature Min Ts _{min}		
Preheat Temperature Max Tsmax		
Preheat Time ts _{min} to ts _{max}	seconds	seconds
Time Maintained bove Temperature T_L		
Time Maintained bove Time t_L	seconds	seconds
Peak lassification Temperature Tp		
Time Within of ctual Peak Temperature tp	seconds	seconds
Ramp own Rate	second max	second max
Time to Peak Temperature	minutes max	minutes max

Note:

recommend to use a convection type reflow machine with zones

°°°°°°°° **mmin**

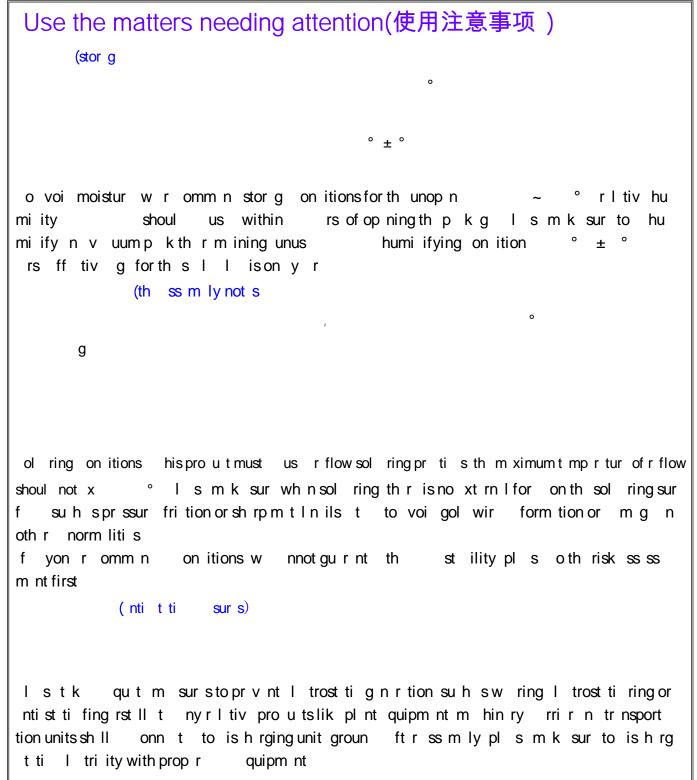
recommend to use Lead ree Paste with a melting point between

the reflow soldering time should not be more than s all temperature means the temperature meas ured on the surface of the package body

s

When using hot plate the temperature is no more than the time is not more than seconds





(t mp r tur ontrol)



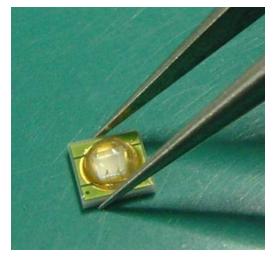
uring ss m ly pl s nsur th t goo qu lity th rm lp st is ppli n istriut v nly ov rth sur f hil using th rm lp t ink m k sur is firmly tight n n th r is nog p tw n sur f s h n to nsur th ooling m ium i l tri withst n t st t l st through (riv ontrol

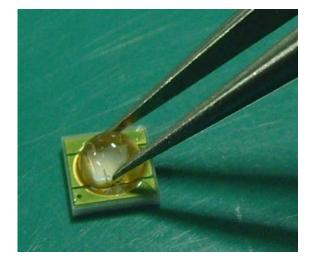
rive this product at constant current Output current range specifications should be according to the operational and other conditions as mentioned in data sheet efore using a con stant voltage source or altered specifications other than recommended please consider risk factors



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Notes注:

Il high power emitter L products mounted on aluminum metal core printed circuit board can be lighted directly but we do not recommend lighting the high power products for more than seconds without a appropriate heat dissipation equipment

, L ring should not be done more than two tim

Reflow soldering should not be done more than two times. The reflow temperature we recommend is

°C,When the temperature exceeds $\$ the product failure of L $\$ can be caused

x t